

RGS60TS65D

650V 30A Field Stop Trench IGBT

V_{CES}	650V
I _{C(100°C)}	30A
V _{CE(sat) (Typ.)}	1.65V
P_D	223W

Features

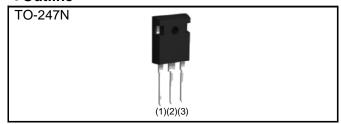
- 1) Low Collector Emitter Saturation Voltage
- 2) Short Circuit Withstand Time 8µs
- 3) Qualified to AEC-Q101
- 4) Built in Very Fast & Soft Recovery FRD
- 5) Pb free Lead Plating; RoHS Compliant

Applications

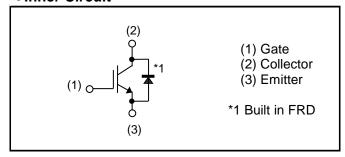
General Inverter

for Automotive and Industrial Use

Outline



●Inner Circuit



Packaging Specifications

	Packaging	Tube
	Reel Size (mm)	-
Tuno	Tape Width (mm)	-
Туре	Basic Ordering Unit (pcs)	450
	Packing Code	C11
	Marking	RGS60TS65D

● Absolute Maximum Ratings (at T_C = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit	
Collector - Emitter Voltage		V _{CES}	650	V	
Gate - Emitter Voltage		V_{GES}	±30	V	
	T _C = 25°C	I _C	56	А	
Collector Current	T _C = 100°C	I _C	30	А	
Pulsed Collector Current	I _{CP} *1	I _{CP} *1 90			
Diode Forward Current	$T_C = 25^{\circ}C$	I _F	56	А	
	T _C = 100°C	I _F	30	А	
Diode Pulsed Forward Current		I _{FP} *1	I _{FP} *1 90		
Power Dissipation	$T_C = 25^{\circ}C$	P_{D}	223	W	
	T _C = 100°C	P_{D}	111	W	
Operating Junction Temperature		T _j	-40 to +175	°C	
Storage Temperature		T_{stg}	−55 to +175	°C	

^{*1} Pulse width limited by T_{jmax.}

●Thermal Resistance

Parameter	Symbol	Values			Unit
Farameter		Min.	Тур.	Max.	Offic
Thermal Resistance IGBT Junction - Case	$R_{\theta(j-c)}$	-	-	0.67	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	-	-	1.17	°C/W

ullet **IGBT Electrical Characteristics** (at $T_j = 25$ °C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Тур.	Max.	Offic
Collector - Emitter Breakdown Voltage	BV _{CES}	$I_C = 10 \mu A, V_{GE} = 0 V$	650	-	-	V
		$V_{CE} = 650V, V_{GE} = 0V$				
Collector Cut - off Current	I _{CES}	T _j = 25°C T _j = 175°C	-	-	10	μΑ
		T _j = 175°C			5	mA
Gate - Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 30V, \ V_{CE} = 0V$	-	-	±200	nA
Gate - Emitter Threshold Voltage	$V_{\text{GE(th)}}$	$V_{CE} = 5V, I_{C} = 1.5 \text{mA}$	5.0	6.0	7.0	V
Collector - Emitter Saturation Voltage		$I_C = 30A, V_{GE} = 15V$				
	$V_{\text{CE(sat)}}$	T _j = 25°C	-	1.65	2.10	V
		T _j = 175°C	-	2.15	-	

ullet **IGBT Electrical Characteristics** (at $T_j = 25$ °C unless otherwise specified)

Davagastav	eter Symbol Conditions -	Conditions		Unit		
Parameter		Min.	Тур.	Max.	Offic	
Input Capacitance	C_{ies}	V _{CE} = 30V	-	980	-	
Output Capacitance	C _{oes}	$V_{GE} = 0V$	-	80	-	pF
Reverse Transfer Capacitance	C _{res}	f = 1MHz	-	13	-	
Total Gate Charge	Q_g	V _{CE} = 300V	-	36	-	
Gate - Emitter Charge	Q_ge	I _C = 30A	-	10	-	nC
Gate - Collector Charge	Q_{gc}	V _{GE} = 15V	-	15	-	
Turn - on Delay Time	t _{d(on)}	$I_C = 30A, V_{CC} = 400V$	-	28	-	
Rise Time	t _r	$V_{GE} = 15V, R_G = 10\Omega$	-	12	-	no
Turn - off Delay Time	$t_{d(off)}$	T _j = 25°C	-	104	-	ns
Fall Time	t _f	Inductive Load	-	101	-	
Turn - on Switching Loss	E_{on}	*E _{on} includes diode	ı	0.66	1	m l
Turn - off Switching Loss	E_{off}	reverse recovery	ı	0.81	-	mJ
Turn - on Delay Time	t _{d(on)}	$I_C = 30A, V_{CC} = 400V$	-	29	-	
Rise Time	t _r	$V_{GE} = 15V, R_{G} = 10\Omega$	-	17	-	no
Turn - off Delay Time	$t_{d(off)}$	T _j = 175°C	-	131	-	ns
Fall Time	t _f	Inductive Load	-	159	-	
Turn - on Switching Loss	E_{on}	*E _{on} includes diode	-	0.88	-	m l
Turn - off Switching Loss	E _{off}	reverse recovery	-	1.13	-	mJ
		$I_C = 90A, V_{CC} = 520V$				
Reverse Bias Safe Operating Area	RBSOA	$V_P = 650 V, V_{GE} = 15 V$	FULL SQUARE			-
		$R_G = 50\Omega, T_j = 175^{\circ}C$				
OL 40: ***********************************		V _{CC} ≦ 360V	0			
Short Circuit Withstand Time	t _{sc}	$V_{GE} = 15V, T_j = 25^{\circ}C$	8	-	-	μs
Short Circuit Withstand Time	t _{sc} *2	$V_{CC} \le 360V$	6	-	-	μs
		$V_{GE} = 15V, T_j = 150^{\circ}C$	Ö			

^{*2} Design assurance without measurement

●FRD Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Тур.	Max.	Offic
Diode Forward Voltage	V_{F}	$I_F = 30A$ $T_j = 25$ °C $T_j = 175$ °C	-	1.45 1.55	1.90 -	V
Diode Reverse Recovery Time	t _{rr}	$I_F = 30A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 25^{\circ}C$	-	103	-	ns
Diode Peak Reverse Recovery Current	I _{rr}		-	7.1	-	А
Diode Reverse Recovery Charge	Q_{rr}		-	0.4	-	μC
Diode Reverse Recovery Energy	E _{rr}		-	15	-	μJ
Diode Reverse Recovery Time	t _{rr}	$I_F = 30A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 175^{\circ}C$	-	242	-	ns
Diode Peak Reverse Recovery Current	I _{rr}		-	9.8	-	А
Diode Reverse Recovery Charge	Q_{rr}		-	1.3	-	μC
Diode Reverse Recovery Energy	E _{rr}		-	113	-	μJ

Fig.1 Power Dissipation vs. Case Temperature

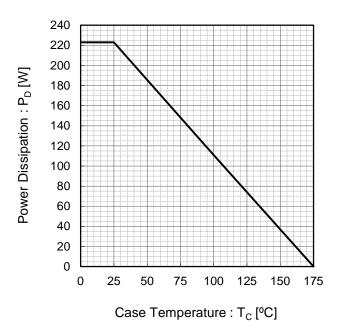
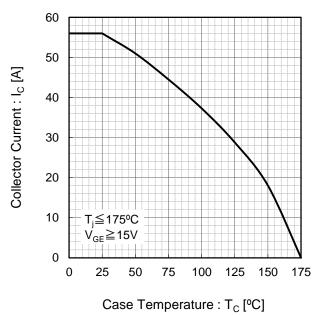


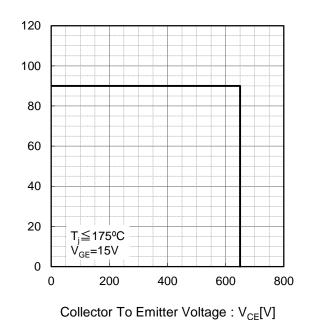
Fig.2 Collector Current vs. Case Temperature



1000 100 100µs 1000 Collector To Emitter Voltage : $V_{CE}[V]$

Fig.3 Forward Bias Safe Operating Area

Fig.4 Reverse Bias Safe Operating Area



Collector Current : I_C [A]

Fig.5 Typical Output Characteristics

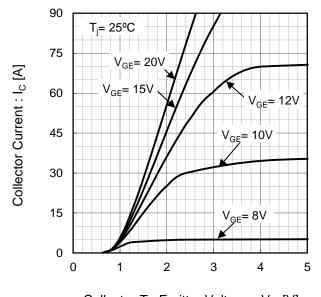
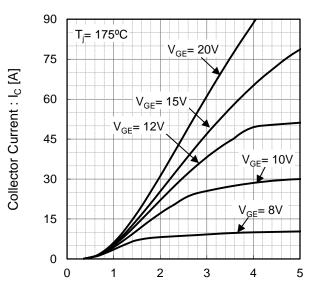


Fig.6 Typical Output Characteristics



Collector To Emitter Voltage : $V_{CE}[V]$

Collector To Emitter Voltage : $V_{CE}[V]$

Fig.7 Typical Transfer Characteristics

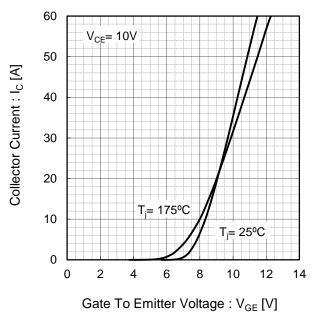


Fig.8 Typical Collector To Emitter Saturation Voltage vs. Junction Temperature

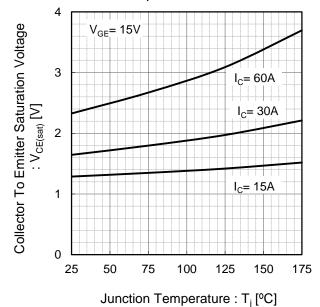
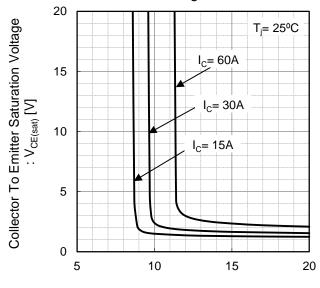
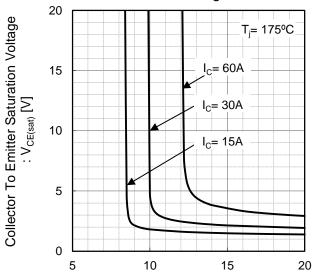


Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate To Emitter Voltage : V_{GE} [V]

Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate To Emitter Voltage: V_{GE} [V]

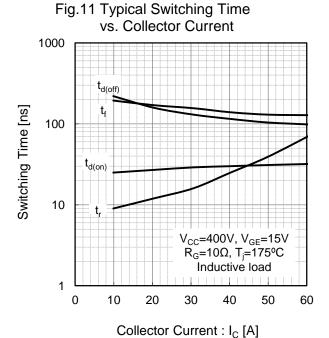


Fig.12 Typical Switching Time vs. Gate Resistance 1000 Switching Time [ns] 100 $t_{d(off)}$ t_{d(on)} 10 V_{CC}=400V, I_C=30A V_{GE}=15V, T_j=175°C Inductive load 10 20 30 50 0 40 Gate Resistance : $R_G[\Omega]$

Fig.13 Typical Switching Energy Losses vs. Collector Current 10 Switching Energy Losses [mJ] $\mathsf{E}_{\mathsf{off}}$ E_{on} 0.1 V_{CC} =400V, V_{GE} =15V R_G=10 Ω , T_j=175°C Inductive load 0.01 40 0 10 20 30 50 60 Collector Current : I_C [A]

vs. Gate Resistance 10 Switching Energy Losses [mJ] $\mathsf{E}_{\mathsf{off}}$ 1 E_{on} 0.1 V_{CC}=400V, I_C=30A V_{GE}=15V, T_j=175°C Inductive load 0.01 0 10 20 30 40 50 Gate Resistance : $R_G[\Omega]$

Fig.14 Typical Switching Energy Losses

Fig.15 Typical Capacitance vs. Collector To Emitter Voltage 10000 Cies 1000 Capacitance [pF] Coes 100 Cres 10 f=1MHz $V_{GE}=0V$ T=25°C 0.01 0.1 1 10 100 Collector To Emitter Voltage : V_{CE}[V]

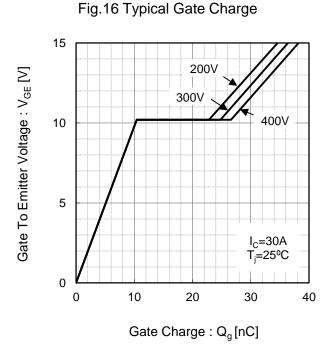


Fig.17 Typical Diode Forward Current vs. Forward Voltage 90 75 Forward Current : I_F [A] 60 45 30 15 T_i= 175°C T_i= 25°C 0 0.5 1.5 2 2.5 3 Forward Voltage : V_F[V]

Fig.18 Typical Diode Reverse Recovery Time vs. Forward Current 400 Reverse Recovery Time: t_{rr} [ns] 300 T_i= 175°C 200 100 V_{CC} =400V di_F/dt=200A/µs $T_i = 25^{\circ}C$ Inductive load 0 40 50 0 20 30 60 10 Forward Current : I_F [A]

Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current 20 Reverse Recovery Current : In [A] 15 T_i= 175°C 10 5 T_i= 25°C V_{CC} =400V di_F/dt=200A/µs Inductive load 0 10 20 30 40 50 60

Forward Current : I_F [A]

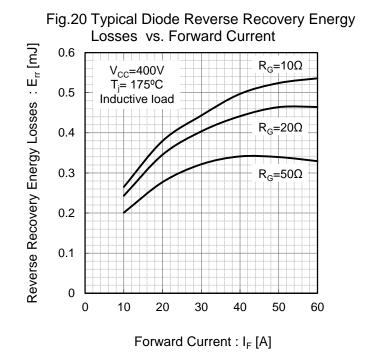
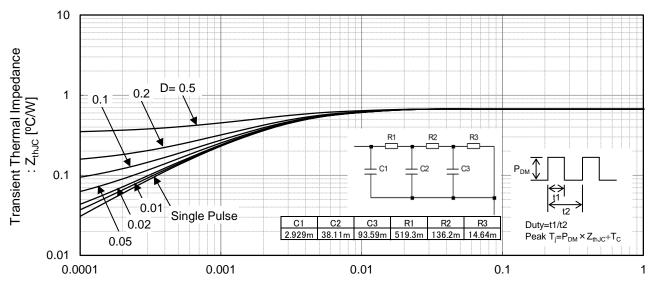
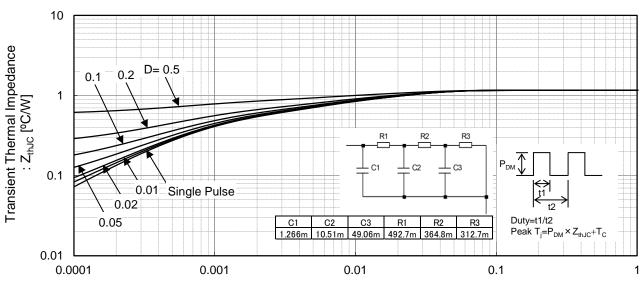


Fig.21 IGBT Transient Thermal Impedance



Pulse Width: t1[s]

Fig.22 Diode Transient Thermal Impedance



Pulse Width: t1[s]

●Inductive Load Switching Circuit and Waveform

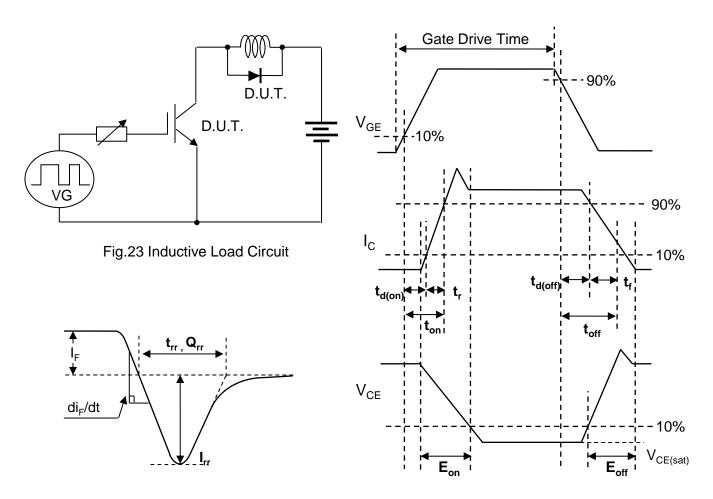


Fig.25 Diode Reverce Recovery Waveform

Fig.24 Inductive Load Waveform

Notes

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